Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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RB751S40

Schottky Barrier Diode

These Schottky barrier diodes are designed for high−speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand−held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage − 0.28 V (Typ) @ I_F = 1.0 mAdc
- Low Reverse Current
- Lead−Free Plating
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	40	V
Reverse Voltage	V_R	30	V
Forward Continuous Current (DC)	I_F	30	mA
Peak Forward Surge Current	I_{FSM}	500	mA
ESD Rating: Class 1C per Human Body Model Class A per Machine Model			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

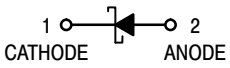
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board, (Note 1) T_A = 25°C Derate above 25°C	P_D	200 1.57	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

1. FR−5 Minimum Pad.

ON Semiconductor®

www.onsemi.com

40 V SCHOTTKY BARRIER DIODE



SOD−523
CASE 502
STYLE 1

MARKING DIAGRAM

5E = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
RB751S40T1G	SOD−523 (Pb−Free)	3000 / Tape & Reel
NSVRB751S40T1G	SOD−523 (Pb−Free)	3000 / Tape & Reel
RB751S40T5G	SOD−523 (Pb−Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage (I_R = 10 μA)	$V_{(BR)R}$	30	–	–	V
Total Capacitance (V_R = 1.0 V, f = 1.0 MHz)	C_T	–	2.0	2.5	pF
Reverse Leakage (V_R = 30 V)	I_R	–	300	500	nAdc
Forward Voltage (I_F = 1.0 mAdc)	V_F	–	0.28	0.37	Vdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

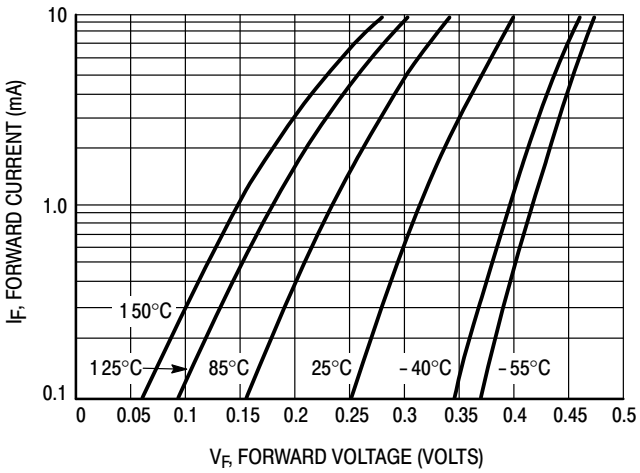


Figure 1. Typical Forward Voltage

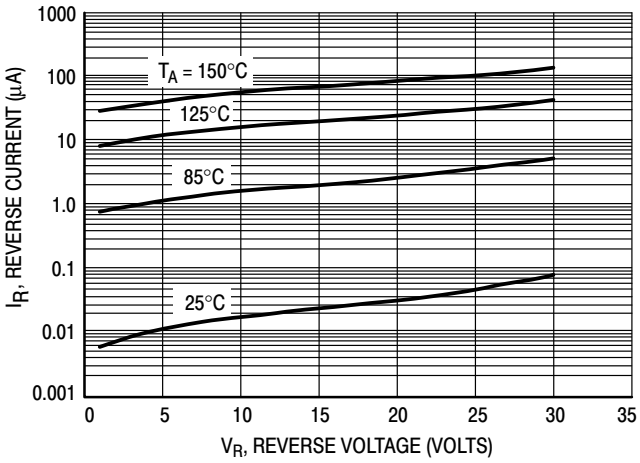


Figure 2. Reverse Current versus Reverse Voltage

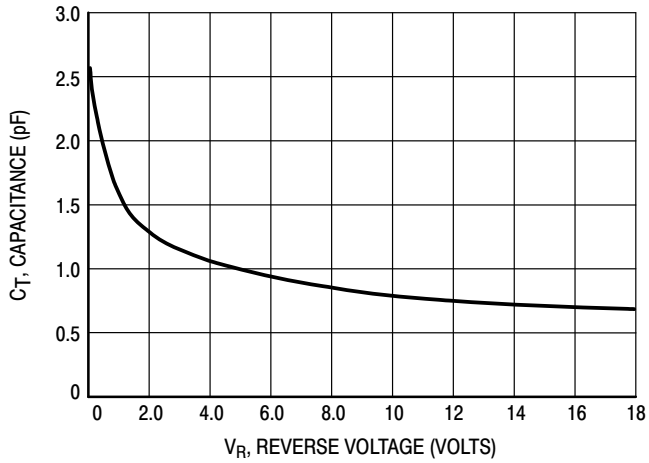


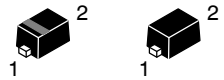
Figure 3. Typical Capacitance

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

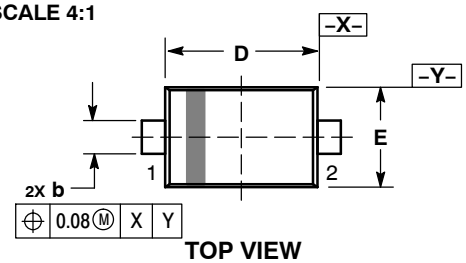
SOD−523
CASE 502−01
ISSUE E

DATE 28 SEP 2010

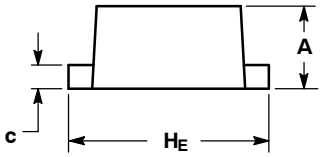


STYLE 1 STYLE 2

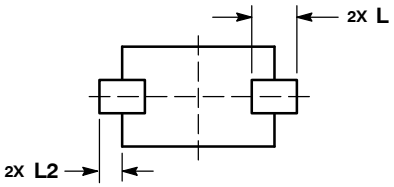
SCALE 4:1



TOP VIEW

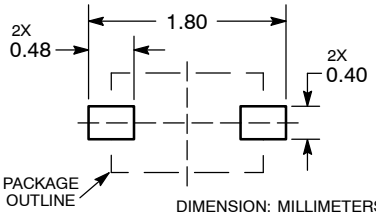


SIDE VIEW



BOTTOM VIEW

RECOMMENDED
SOLDERING FOOTPRINT*



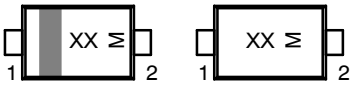
DIMENSION: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.50	0.60	0.70
b	0.25	0.30	0.35
c	0.07	0.14	0.20
D	1.10	1.20	1.30
E	0.70	0.80	0.90
HE	1.50	1.60	1.70
L	0.30 REF		
L2	0.15	0.20	0.25

GENERIC
MARKING DIAGRAM*



STYLE 1 STYLE 2

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2:
NO POLARITY

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SOD−523	PAGE 1 OF 2

ISSUE	REVISION	DATE
A	ADDED CATHODE BAND. REQ. BY M. DEWITT	07 JUL 2004
B	UPDATED FOOTPRINT AND MARKING. REQ. BY S. WEST.	21 FEB 2005
C	CREATED CATHODE AND NON−CATHODE BAND OPTIONS. REQ. BY J. DAUGHERTY.	13 MAR 2007
D	CHANGED DIMENSION LABELS TO MATCH CURRENT STANDARDS. REQ. BY D. TRUHITTE.	27 JAN 2009
E	ADDED BOTTOM VIEW/UPDATED SOLDER FOOTPRINT. REQ. BY D. TRUHITTE.	28 SEP 2010

PUBLICATION ORDERING INFORMATION

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